11-24-2000 11-05-00 NON 05 3000 Atty Docket No: SEL 192 101525548 OFFICE THE UNITED I hereby certify that this correspondence In re application of: Yamazaki et al. is being deposited with the United States Serial No: 09/610,217 Postal Service as first class mail in an Filed: July 5, 2000 envelope addressed to: For: Semiconductor Device And Fabrication Method Thereof Commissioner for Patents, Washington, Art Unit: D.C. 20231, on October 31, 2000 Examiner: PATENT ASSIGNMENT COVER SHEET Assistant Commissioner for Patents Washington, D. C. 20231 Please record the attached original document or copy thereof. Total numb@atef_pages (with cover sheet): 2 Sir: Name of Conveying Party(ies): Name and Address of Party to Whom Shunpei YAMAZAKI, Yasuyuki ARAI and Jun KOYAMA Correspondence Concerning Document Should be Mailed 2a. Name and Address of Receiving Party(ies): Edward D. Manzo, Esq. Name: Semiconductor Energy Laboratory Co., Ltd. COOK, ALEX, McFARRON, MANZO, CUMMINGS & Address: 398, Hase, Atsugi-shi, Kanagawa-ken MEHLER, LTD. 243-0036 Japan 200 West Adams Street, Suite 2850 Chicago, Illinois 60606 2b. Name and Address of Receiving Party(ics): 6. Total Number of Applications and Patents Name: Address Involved: 1 7. Nature of Conveyance Total Fee (37 CFR 3.41): \$40.00 X Assignment 7a. X Enclosed __Merger 7b. X Authorized to be Charged to Deposit _Security Agreement Account For Any Deficiency Change of Name Deposit Account Number: 50/1039 Other X Execution Date: 9/19/00; 9/22/00 (A duplicate copy of this page is attached) Application Number(s) or Patent number(s) (If this Statement and Signature: To the best of my knowledge and belief, the foregoing document is being filed together with a new application, the execution date of the application is: _____) information is true and correct and any attached copy is a

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4a. Patent Application No.(s) 09/610,217

4b. Patent No.(s)

true copy of the original document.

Mark J. Murphy

Name of Person Signing

Date: October 30, 2000

Signature Reg. No. 34,225

ASSIGNMENT

Identity Of The Patent Application. I am the inventor (or one joint inventor) of a patent application that I am assigning. The patent application I am assigning is entitled <u>SEMICONDUCTOR DEVICE AND FABRICATION METHOD THEREOF</u> which I executed herewith. If the patent application has already been filed, it received serial number 09/610,217 and bears a filing date of <u>July 5, 2000</u>.

The Assignee and The Assignment. I assign my patent rights to Semiconductor Energy Laboratory Co., Ltd. a corporation organized according to the laws of Japan, having a place of business at 398. Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan (hereinafter "the Assignee"). The rights I assign are my entire right, title and interest in the invention or improvements disclosed in the patent application and any and all other applications for United States Letters Patent which I may file, either solely or jointly with others, on the invention or improvements, including all continuations, divisionals, and continuations-in-part, and in any and all United States Letters Patent which may be obtained on any of said applications, and in any reissue or extension thereof. I also assign to the Assignee all priority rights under the International Convention. I agree to execute, at the request of the Assignee, all documents in connection with any application for United States letters patent therefor.

Payment Received. I am making this assignment in consideration of One Dollar and other good and valuable consideration. I acknowledge the receipt and sufficiency of the consideration.

Authorizations. I request the U.S. Commissioner of Patents and Trademarks to issue the Letters Patent to the Assignee. I authorize the attorney(s) of record in the application to insert in this assignment document the date and serial number of the application.

Further Acts. I agree, upon the request and at the expense of the Assignee, to execute any divisional, continuation or substitute application for the invention or improvements, and any oath, declaration or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon the application. I agree to perform, upon request, any affirmative acts to obtain said Letters Patent of the United States and to vest in the Assignee all rights therein, so that the Letters Patent will be held and enjoyed by the Assignee, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me if this assignment had not been made.

Interference. In the event that any application or Letters Patent that I now assign becomes involved in interference, I agree to cooperate to the best of my ability in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof.

Name. Shunpei YAMAZAKI	01199 7866
Name. Shunpei YAMAZAKI	Date
Name: Yasayuki ARAI	09/22/2000 Date
Jun Noyama Name: Jun KOYAMA	09/22/2000 Date
Name:	Date

PATENT
RECORDED: 11/02/2000 REEL: 011255 FRAME: 0741